

# SDB110LFW-AH

## Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 100 V

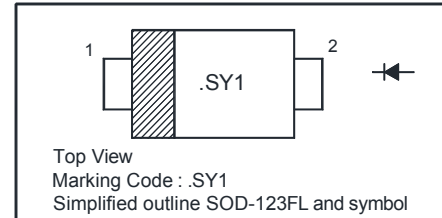
Forward Current - 1 A

### Features

- AEC-Q101 Qualified
- Guardring for Stress Protection
- Low Forward Voltage
- Halogen and Antimony Free(HAF), RoHS compliant

### PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | Cathode     |
| 2   | Anode       |



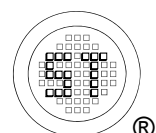
### Absolute Maximum Ratings and Characteristics

Ratings at  $T_a = 25^\circ\text{C}$  ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Parameter                                                                                         | Symbols         | Value         | Units               |
|---------------------------------------------------------------------------------------------------|-----------------|---------------|---------------------|
| Maximum Recurrent Peak Reverse Voltage                                                            | $V_{RRM}$       | 100           | V                   |
| Maximum DC Blocking Voltage                                                                       | $V_{DC}$        | 100           | V                   |
| Maximum Average Forward Rectified Current                                                         | $I_{F(AV)}$     | 1             | A                   |
| Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method) | $I_{FSM}$       | 50            | A                   |
| Forward Voltage<br>at $I_F = 1\text{ A}$<br>at $I_F = 2\text{ A}$                                 | $V_F$           | 0.76<br>0.84  | V                   |
| Reverse Current<br>at $V_R = V_{RRM}$<br>at $V_R = V_{RRM}$ , $T_j = 125^\circ\text{C}$           | $I_R$           | 40<br>0.5     | $\mu\text{A}$<br>mA |
| Thermal Resistance Junction to Lead <sup>1)</sup>                                                 | $R_{\theta JL}$ | 23            | $^\circ\text{C/W}$  |
| Thermal Resistance Junction to Ambient <sup>1)</sup>                                              | $R_{\theta JA}$ | 85            | $^\circ\text{C/W}$  |
| Thermal Resistance Junction to Ambient <sup>2)</sup>                                              | $R_{\theta JA}$ | 330           | $^\circ\text{C/W}$  |
| Storage and Operating Junction Temperature Range                                                  | $T_j, T_{stg}$  | - 55 to + 150 | $^\circ\text{C}$    |

<sup>1)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Electrical characteristic curves

Fig 1. Reverse Characteristics

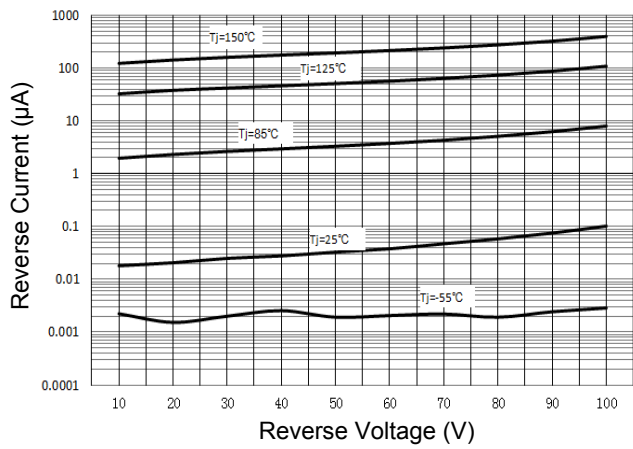


Fig 2. Forward Characteristics

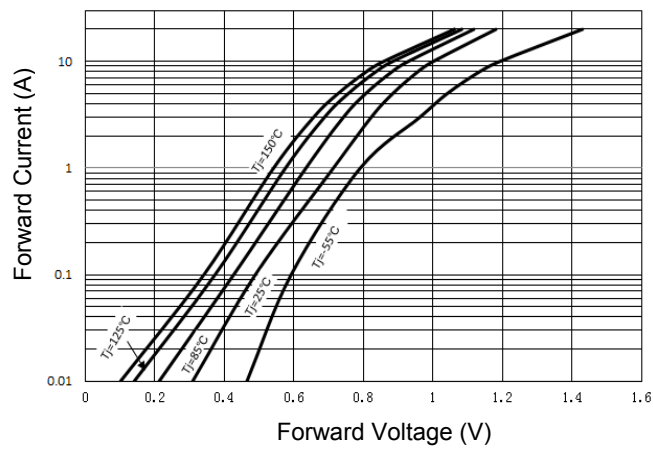
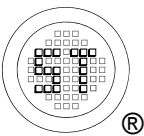
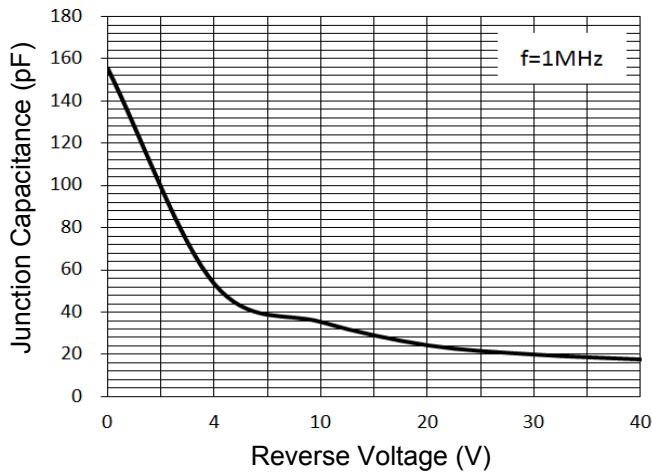


Fig 3. Junction Capacitance

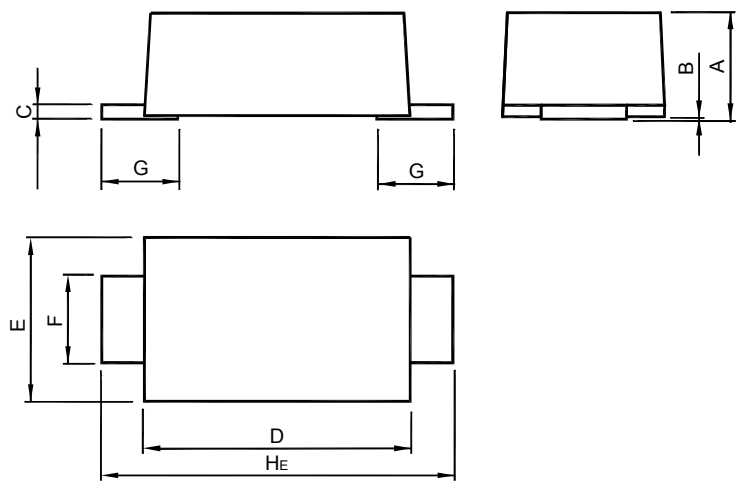


# SDB110LFW-AH

## PACKAGE OUTLINE

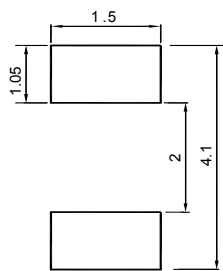
Plastic surface mounted package; 2 leads

SOD-123FL



| UNIT | A            | B        | C          | D          | E          | F          | G            | H <sub>E</sub> |
|------|--------------|----------|------------|------------|------------|------------|--------------|----------------|
| mm   | 1.08<br>0.88 | 0.1<br>0 | 0.2<br>0.1 | 2.9<br>2.7 | 1.9<br>1.7 | 1.1<br>0.8 | 0.85<br>0.45 | 3.9<br>3.5     |

## Recommended Soldering Footprint



## Packing information

| Package   | Tape Width (mm) | Pitch   |               | Reel Size |      | Per Reel Packing Quantity |
|-----------|-----------------|---------|---------------|-----------|------|---------------------------|
|           |                 | mm      | inch          | mm        | inch |                           |
| SOD-123FL | 8               | 4 ± 0.1 | 0.157 ± 0.004 | 178       | 7    | 3,000                     |

## Marking information

" III " = Cathode line  
" • " = HAF (Halogen and Antimony Free)  
" SY1 " = Part No.  
Font type: Arial

